

In the Specification

Amend the title as follows:

Methods for Conditioning Surfaces of Polishing Pads After Chemical-Mechanical Polishing,  
~~and Apparatuses for Conditioning Surfaces of Polishing Pads~~

RELATED PATENT DATA

This patent resulted from a divisional application of U.S. Patent Application Serial No. 10/075,172, which was filed February 13, 2002.